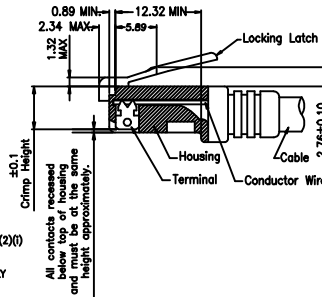
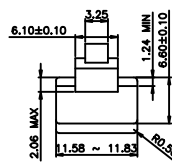
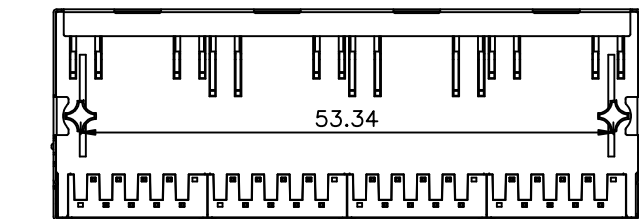
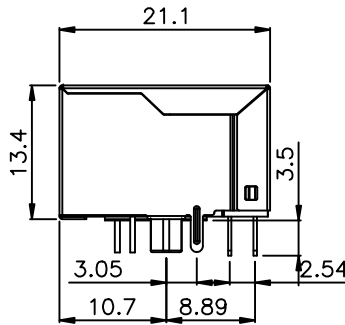
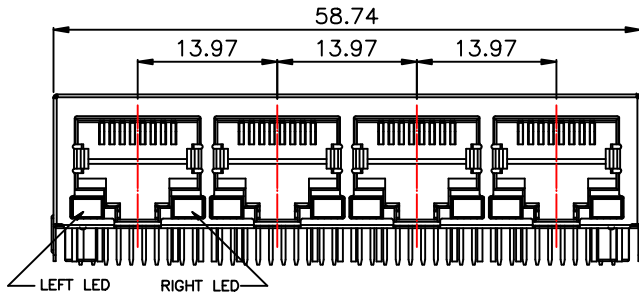
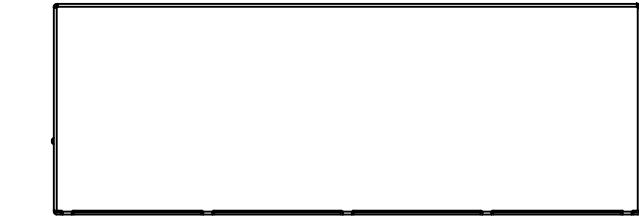
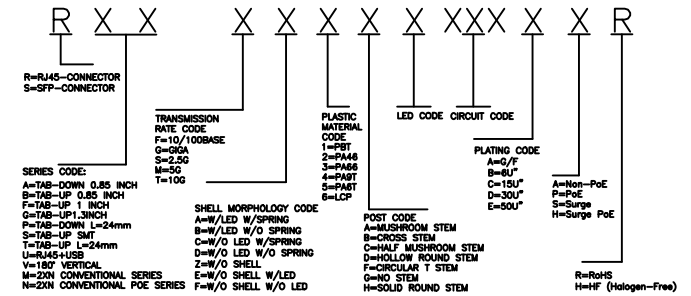


REV	ECN NO	DESCRIPTION	DATE
A	/	New Drawing	2025/4/10

- THE PRODUCT IS ROHS COMPLIANT.
- ALL DIMENSIONS FOLLOW :  
 -FCC SUBPART F, 68,500, FIGURE (C)(2)(I) & (C)(2)(II) & (C)(3)(I) IEC 60603-7  
 -ALL PLUGS MUST BE MEETING THE REQUIREMENTS OF PLUG GO & NO-GO GAUGE.
- GAUGE FOLLOW : FCC SUBPART F, 68,500, FIGURE (C)(4)(I) & (C)(5)(I)  
 -THERE MUST BE NO DAMAGE TO HOUSING AND LOCKING LATCH.  
 -THERE MUST BE NO NICKS AND CUTS IN CABLE.
- PART CAN BE RECOMMENED FOR REFLOW SOLDERING PROCESS.  
 PEAK REFLOW SOLDERING TEMPERATURE IS 260°C MAX,10SECONDS MAX.
- OPERATING TEMPERATURE:-40 TO +85°C;
- STORAGE TEMPERATURE: -40 TO +85°C

- MATERIAL:
  - HOUSING: HIGH TEMPERATURE THERMOPLASTIC PA46.  
 FLAMMABILITY RATING ,UL 94V-0; COLOR:BLACK.
  - SHELL: BRASS C2680H, THICKNESS=0.20mm.PLATING NICKEL 30u"Min;
  - RJ TERMINAL: THERMOPLASTIC PBT,COLOR:BLACK;  
 UL 94V-0;  
 PIN:THICKNESS=0.30mm.PHOS-BRONZE C5210EH.  
 PLATING: 50u" MIN NICKEL UNDERPLATING ALL AREA.  
 100u" MIN TIN ON SOLDER TAIL.
  - INPUT TERMINAL: PHY PIN:THICKNESS=0.30mm. BRASS C2680H.  
 LED PIN:THICKNESS=0.45mm. BRASS C2680H.  
 PLATING: 50u" MIN NICKEL UNDERPLATING ALL AREA.  
 100u" MIN TIN ON SOLDER TAIL.

8.CODING PRINCIPLES



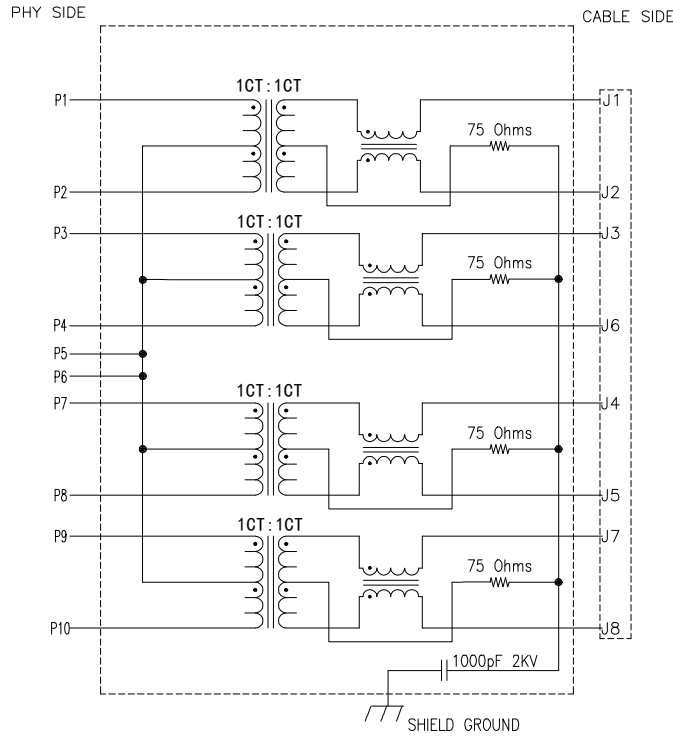
All dimensions follow :  
 FCC subpart F, 68,500, Figure (C)(2)(I)  
 IEC 60603-7  
 STANDARD MODULAR PLUG ASSEMBLY

All contacts recessed relative to housing and height approximately.

X. ± 0.40	APPD: LH.WANG	深圳市金航标电子有限公司	
.X ± 0.30	CHKD: LOUIS	PART NO: KH-RA4-SB2B2002DAR	
.XX ± 0.25	DR: LIANG	TITLE: TAB DOWN 1X4Port 2.5G BASE-T RJ45 JACK Magnetics	
.XXX ± 0.20	UNITS: mm	REMARK: XXX-XXXX	
X' ± 3'	SCALE: 1:1	REVISION: A	DATE: RA4-0072
X'' ± 2'	SHEET: 1 OF 2	DWG NO: RA4-0072	REMARK: XXX-XXXX
UNITS: mm	SCALE: 1:1	REVISION: A	DATE: RA4-0072



REV	ECN NO	DESCRIPTION	DATE
A	/	New Drawing	2025/4/10



D. ELECTRICAL SPECIFICATIONS @25°C

TRANSMITTER FILTER & RECEIVER FILTER

TYPE : BALANCE LOW PASS 100Ω IMPEDANCE

INSERTION LOSS : 125~200MHz -2.0dB MAX.

RETURN LOSS : 1~30MHz -18DB MIN. LOAD 100Ω  
-16+10log(f/40) dB Min @ 40< f ≤250 MHz,

COMMON MODE REJECTION  
@1~250 MHz -30dB MIN.

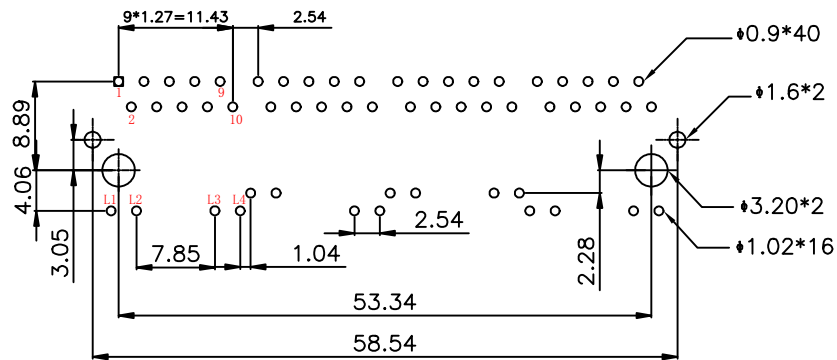
CROSS TALK  
@ 1~100MHz -30dB MIN.

INDUCTANCE (OCL) @ 100KHz, 0.1V, 8mA DC BIAS 180 uH MIN.

DCR:1.0 OHM MAX

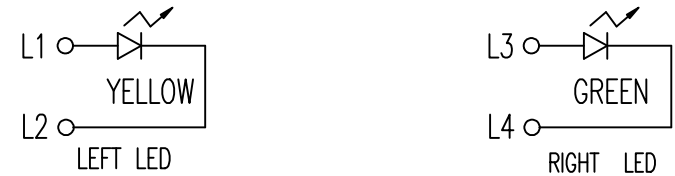
HIPOT TEST  
PHY SIDE(INPUT) TO CABLE SIDE(OUTPUT) : 1500Vrms 60S

C:PIN ASSIGNMENT FOR PCB LAYOUT



SUGGESTED PCB PAD LAYOUT  
COMPONENT SIDE VIEW

E:LED SPECIFICATION



Emitting Color	λp (nm)	Vf @If=20mA	Ir @Vr=5V
GREEN	570	1.7 ~2.6 V	10mA max
YELLOW	590	1.7 ~2.6 V	10mA max

X. ± 0.40	APPD: LH.WANG	深圳市金航标电子有限公司	
.X ± 0.30	CHKD: LOUIS	PART NO: KH-RA4-SB2B2002DAR	
.XX ± 0.25	DR: LIANG	TITLE: TAB DOWN 1X4Port 2.5G BASE-T RJ45 JACK Magnetics	
.XXX ± 0.20	UNITS: mm	REMARK: XXX-XXXX	
X' ± 3'		SHEET: 2 OF 2	REVISION: A
		SCALE: 1:1	DWG NO: RA4-0072

